



ENGINEERING DEPT.		PRODUCT SPECIFICATION For CP15 Series Connector System	SPEC.NO.: SPCP075C
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1. SCOPE:

This specification contains the test requirement of subject connectors when tested under the condition and procedure with terminals crimped on the specified maximum size wire

2. APPLICABLE STANDARDS:

MIL - STD - 202	Methods for test of connectors for electronic equipment
EIA-364	Test methods for electrical connectors
J-STD-020	Resistance to soldering Temperature for through hole Mounted Devices
SS-00254	Test methods for electronic components , LEAD-FREE soldering Part design standards

3. APPLICABLE SERIES NO.: CP15 Series

4. SHAPE, CONSTRUCTION AND DIMENSIONS

See attached drawings

5. MATERIALS

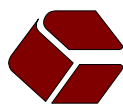
See attached drawings

6. ACCOMMODATED P.C.BOARD

6.1 P.C. Board Layout: See attached drawings



REVIEWED : Eisley APPROVED : Sun VERIFIED : Eric .

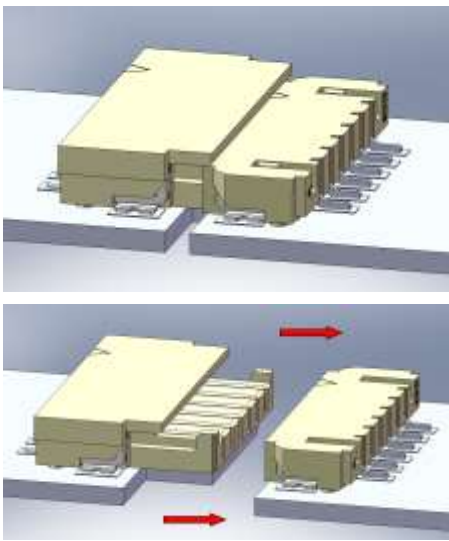


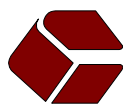
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7. ELECTRICAL PERFORMANCE:

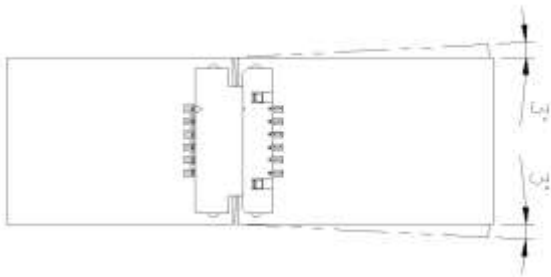
	ITEM	TEST CONDITION	REQUIREMENT
7.1	Rated current and voltage		2~5Pin: 1.0A 150V AC (r.m.s) 3Pin Omitted Pin No. 2: 1.0A 250V AC (r.m.s)
7.2	Contact resistance	Dry circuit of DC 20 mV max. , 10 mA max.	Less than 20 mΩ
7.3	Dielectric strength	2~5Pin: When applied AC 1300 V 1 minute between adjacent terminal	No change
		3Pin Omitted Pin No. 2: When applied AC 1500 V 1 minute between adjacent terminal	
7.4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground	More than 1000 MΩ

8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Pin retention force in Board mount Header	Push Pin for insulator base at speed 25 ± 3 mm per minute	More than 0.3 kgf
8.2	Locking retention force against horizontal pulling	Speed 25 ± 3 mm per minute 	More than 1.5 kgf

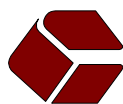


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	ITEM	TEST CONDITION	REQUIREMENT
8.3	Durability	Connector shall be subjected to 10 cycles of insertion and withdrawal	Contact resistance: Less than twice of initial
8.4	horizontal movable angle		Appearance: No damage

9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Temperature rise	Then carried the rated current	30 °C max.
9.2	Vibration	1.5 mm 10-55-10 HZ/minute each 2 hours for X, Y and Z directions	Appearance: No damage Discontinuity: 1 micro second max.
9.3	Heat aging	85± 2 °C, 96 hours	No damage
9.4	Humidity	60± 2 °C, 90-95% RH, 96 hours measurement must be taken within 30 min. after tested	Appearance: No damage Contact resistance: Less than twice of initial Dielectric strength: To pass para 7-3
9.5	Temperature cycling	One cycle consists of : (1) -55 $\begin{smallmatrix} +0 \\ -3 \end{smallmatrix}$ °C , 30 min. (2) Room temp. 10-15 min. (3) 85 $\begin{smallmatrix} +3 \\ -0 \end{smallmatrix}$ °C , 30 min. (4) Room temp. 10-15 min. Total cycles : 5 cycles	Appearance: No damage Contact resistance: Less than twice of initial



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	ITEM	TEST CONDITION	REQUIREMENT
9.6	Salt spray	Temperature: $35 \pm 3^{\circ}\text{C}$ Solution: $5 \pm 1\%$ Spray time: 48 ± 4 hours (Stamping before plated) Spray time: 24 ± 4 hours (Stamping after plated) Mate connectors and expose to the following salt mist conditions. Upon completion of the exposure period, salt deposits shall be removed by a gentle wash or dip in running water and dried naturally, after which the specified measurements shall be performed. The specimens shall be suspended from the top using waxed twine, string or nylon thread. The test only define the plating area, without plating area (as copper cross section) will not be defined. (EIA 364-26B / MIL-STD-202 Method 101)	Appearance: No damage on function Contact resistance: Less than twice of initial
9.7	Solder ability	Lead-Free Process: Soldering time: 3 ± 0.5 second Soldering pot: $245 \pm 5^{\circ}\text{C}$	Minimum: 90% of immersed area
9.8	Resistance to soldering heat	Lead-Free Process for SMT Type: Refer Reflow temperature profile(11.1)	No damage

10. AMBIENT TEMPERATURE RANGE: -25 to $+85^{\circ}\text{C}$



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11. Recommended IR Reflow Temperature Profile:

11.1 Using Lead-Free Solder Paste

